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Name of conveying party(ies)/Execution Date(s):	2. Name and address of receiving party(ies)
NAOTAKA TSUNODA (01/22/2002) AND KOJI	1
NAGENO (01/25/2002)	
	Name: SONY CORPORATION
	Internal Address:
Execution Date(s); in parentheses after inventor name	Street Address:
Additional name(s) of conveying party(les) attached? Yes X No	1-7-1 Konan, Minato-ku
3. Nature of Conveyance:	Tokyo
│┌ ┤	108-0075
	JAPAN
Security Agreement Change of Name	City:
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· · · · · · · · · · · · · · · · · · ·	his document is being filed together with a new application. B. Patent No.(s)
A. Patent Application No.(s)	7,245,736
	1-1-1,1-1
Additional numbers attached?	Tyes XNo
	
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Darren M. Simon	
LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1,21(h) & 3.41) \$ 40.00
,	
Internal Address: Atty. Dkt.; SONYJP 3,3-744 CONT	Authorized to be charged by credit card
Street Address: 600 South Avenue West	X Authorized to be charged to deposit account
	Enclosed
	None required (government interest not affecting tille)
City: Westfield	8. Payment Information
State: NJ zip: 07090	a, Credit Card Last 4 Numbers
Phone Number: (908) 518-6316	Expiration Date
Fax Number: (908) 654-0415	b. Deposit Account Number 12-1095
Email Address:rcohen@ldlkm.com	Authorized User Name Darren M. Simon
9. Signature:	
- Tour M. Imore	January 31, 2008
Signature NA Simon 47 046	Date Total number of pages including cover 2
Darren M. Simon - 47,946 Name of Person Signing	sheet, attachments, and documents:

843959_1.DOC

PATENT REEL: 020442 FRAME: 0470

S01P0052US00 Docket Number 6640/63437

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in https://www.heapthcommons.org/replication for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at6~7-35 Kitashinagawa, Shinagawa-Ku, Tokyo, Japan (hereinafter reference as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number 09/914,976 Filing Date 12/28/00

PATENT REEL: 020442 FRAME: 0471

S01P0052US00

This assignment executed on the dates indicated below.

<u>Naotaka Tsunoda</u> Execution date of U.S. Patent Application Name of first or sole inventor <u>Tokyo, Japan</u> Residence of first or sole inventor Jan 22 ,2002

Date of this assignment Martika Isrenode Signature of first or sole inventor <u>Koji Nageno</u> Execution date of U.S. Patent Application Name of second inventor <u>Tokvo, Japan</u> Residence of second inventor Jan 21 2002 Signature of second inventor Date of this assignment

PATENT

REEL: 020442 FRAME: 0472